

TABLE 1						
Variant	Label text					
001						
002						

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SUN REV:	Not In VersionControl
IGNORE -> Top Overlay				
PLOT NAME = Top Assembly Drawing	GENERATED : 3/20/2	2013 9:06:33	AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP8921	REV: A	SUN REU	: Not In VersionControl
	Bottom Overlay <- January			Bottom Ove
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/20/2	2013 9:06:33	AM	TEXAS INSTRUMENTS

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